

## 1. General description

Planar passivated very sensitive gate four quadrant triac in a TO92 plastic package intended for use in applications requiring direct interfacing to logic ICs and low power gate drivers.

## 2. Features and benefits

- High blocking voltage capability
- Very sensitive gate
- Planar passivated for voltage ruggedness and reliability
- Triggering in all four quadrants
- Direct interfacing to logic level ICs
- Direct interfacing to low power gate drive circuits

## 3. Applications

- Industrial process control
- General purpose low power motor control
- Home appliances
- Low power AC Fan controllers

## 4. Quick reference data

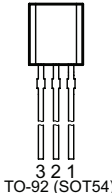
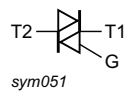
Table 1. Quick reference data

Symbol	Parameter	Conditions	Notes	Values			Unit
Absolute maximum rating							
V <sub>DRM</sub>	repetitive peak off-state voltage			800			V
I <sub>T(RMS)</sub>	RMS on-state current	full sine wave; Fig. 1; Fig. 2		2			A
I <sub>TSM</sub>	non-repetitive peak on-state current	full sine wave; T <sub>j(init)</sub> = 25 °C; t <sub>p</sub> = 20 ms; Fig. 3; Fig. 4		16			A
		full sine wave; T <sub>j(init)</sub> = 25 °C; t <sub>p</sub> = 16.7 ms		17.5			A
T <sub>j</sub>	operating junction temperature			-40 to 125			°C
Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
Static characteristics							
I <sub>GT</sub>	gate trigger current	V <sub>D</sub> = 12 V; I <sub>T</sub> = 0.1 A; T2+ G+; T <sub>j</sub> = 25 °C; Fig. 6		-	-	5	mA
		V <sub>D</sub> = 12 V; I <sub>T</sub> = 0.1 A; T2+ G-; T <sub>j</sub> = 25 °C; Fig. 6		-	-	5	mA
		V <sub>D</sub> = 12 V; I <sub>T</sub> = 0.1 A; T2- G-; T <sub>j</sub> = 25 °C; Fig. 6		-	-	5	mA
		V <sub>D</sub> = 12 V; I <sub>T</sub> = 0.1 A; T2- G+; T <sub>j</sub> = 25 °C; Fig. 6		-	-	10	mA
I <sub>H</sub>	holding current	V <sub>D</sub> = 12 V; T <sub>j</sub> = 25 °C; Fig. 8		-	-	10	mA
V <sub>T</sub>	on-state voltage	I <sub>T</sub> = 2 A; T <sub>j</sub> = 25 °C; Fig. 9		-	1.35	1.65	V

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
<b>Dynamic characteristics</b>							
$dV_D/dt$	rate of rise of off-state voltage	$V_{DM} = 536 \text{ V}$ ; $T_j = 110 \text{ }^\circ\text{C}$ ; ( $V_{DM} = 67\%$ of $V_{DRM}$ ); exponential waveform; gate open circuit; <a href="#">Fig. 11</a>		20	-	-	V/ $\mu\text{s}$
$dV_{com}/dt$	rate of change of commutating voltage	$V_D = 400 \text{ V}$ ; $T_j = 110 \text{ }^\circ\text{C}$ ; $dI_{com}/dt = 0.44 \text{ A/ms}$ ; $I_T = 1 \text{ A}$ ; gate open circuit		1	-	-	V/ $\mu\text{s}$

## 5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	T2	main terminal 2	 <p>TO-92 (SOT54)</p>	 <p>sym051</p>
2	G	gate		
3	T1	main terminal 1		

## 6. Ordering information

Table 3. Ordering information

Type number	Package Name	Orderable part number	Packing method	Small packing quantity	Package version	Package issue date
BT232-800D	TO92	BT232-800D,412	Bulk	1000	TO92L	10-May-2021

## 7. Marking

Table 4. Marking codes

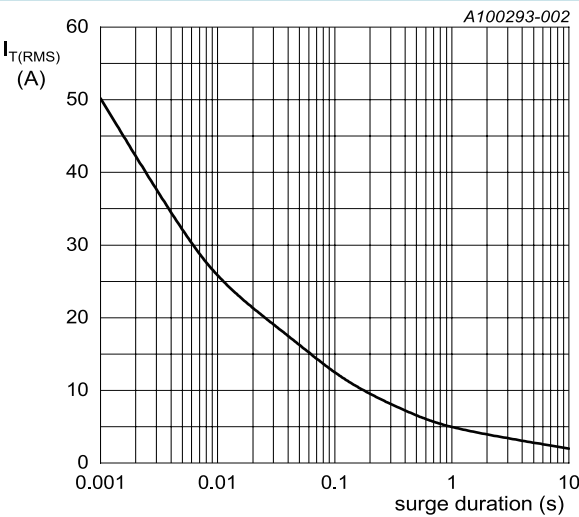
Type number	Marking codes
BT232-800D	232-8D

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

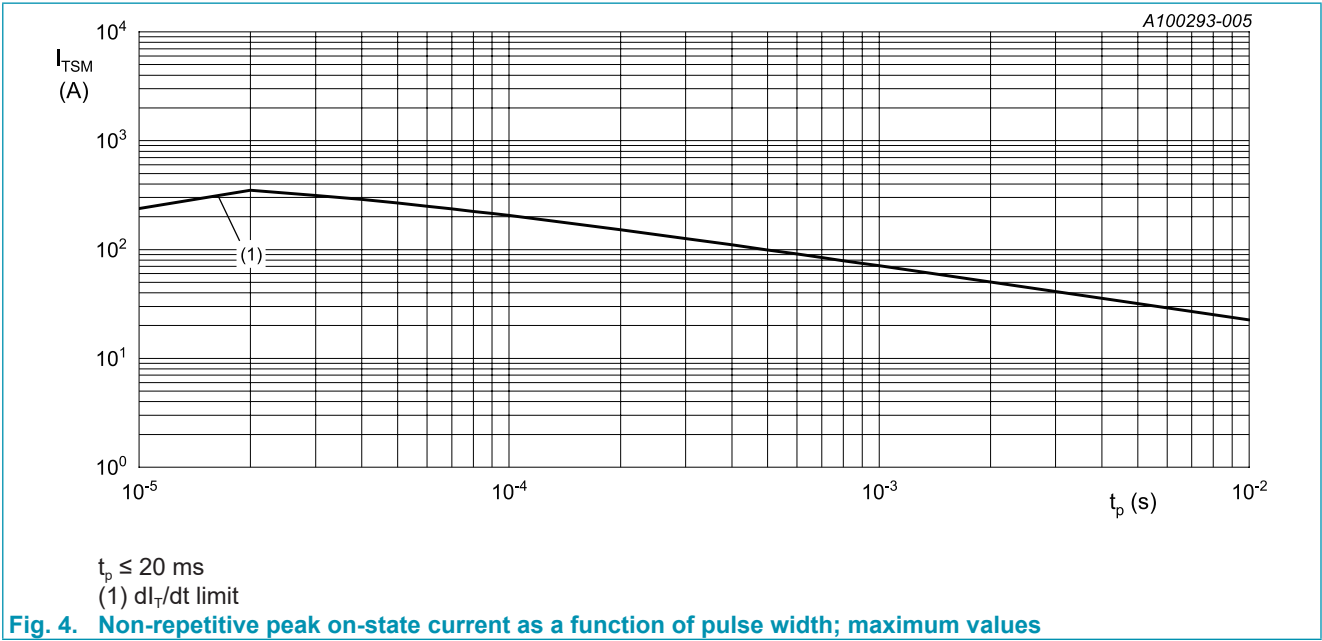
Symbol	Parameter	Conditions	Notes	Values	Unit
$V_{DRM}$	repetitive peak off-state voltage			800	V
$V_{RRM}$	repetitive peak reverse voltage			800	V
$I_{T(RMS)}$	RMS on-state current	full sine wave; Fig. 1; Fig. 2		2	A
$I_{TSM}$	non-repetitive peak on-state current	full sine wave; $T_{j(init)} = 25\text{ }^{\circ}\text{C}$ ; $t_p = 20\text{ ms}$ ; Fig. 3; Fig. 4		16	A
		full sine wave; $T_{j(init)} = 25\text{ }^{\circ}\text{C}$ ; $t_p = 16.7\text{ ms}$		17.5	A
$I^2t$	$I^2t$ for fusing	$t_p = 10\text{ ms}$ ; SIN		1.28	$\text{A}^2\text{s}$
$di_T/dt$	rate of rise of on-state current	$I_G = 20\text{ mA}$		50	$\text{A}/\mu\text{s}$
$I_{GM}$	peak gate current			1	A
$P_{GM}$	peak gate power			2	W
$P_{G(AV)}$	average gate power	over any 20 ms period		0.1	W
$T_{stg}$	storage temperature			-40 to 150	$^{\circ}\text{C}$
$T_j$	operating junction temperature			-40 to 125	$^{\circ}\text{C}$



f = 50 Hz

Fig. 1. RMS on-state current as a function of surge duration; maximum values





9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-lead)}$	thermal resistance from junction to lead	full cycle; Fig. 5	-	40	-	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient free air	full cycle; printed circuit board: lead length = 4 mm	-	150	-	K/W

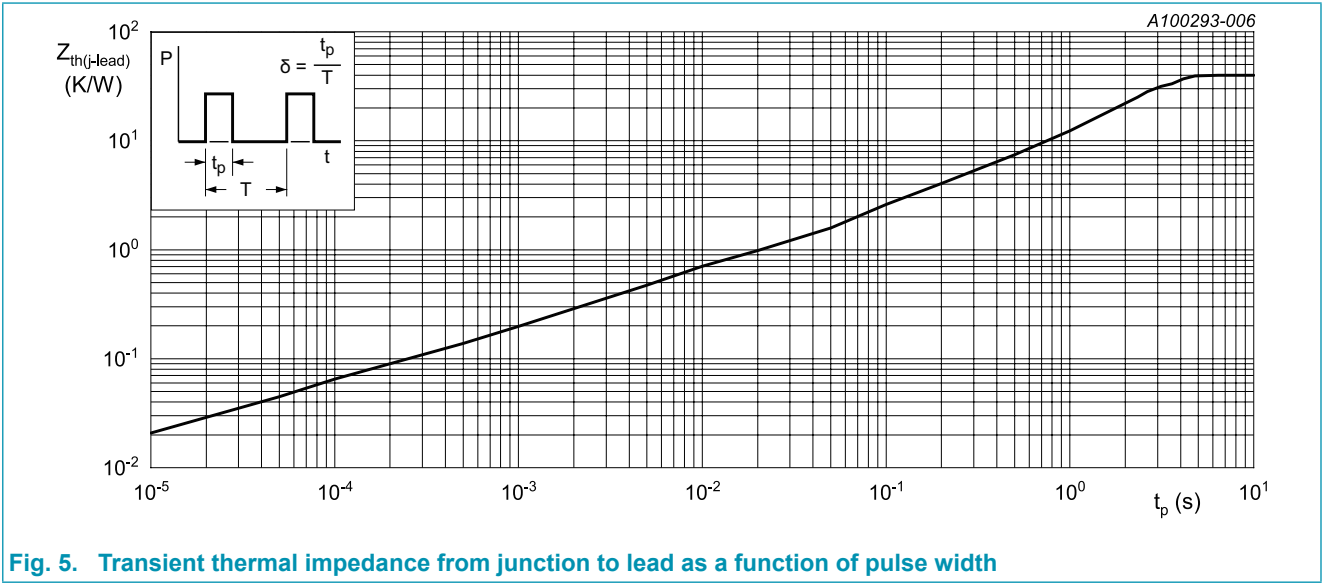
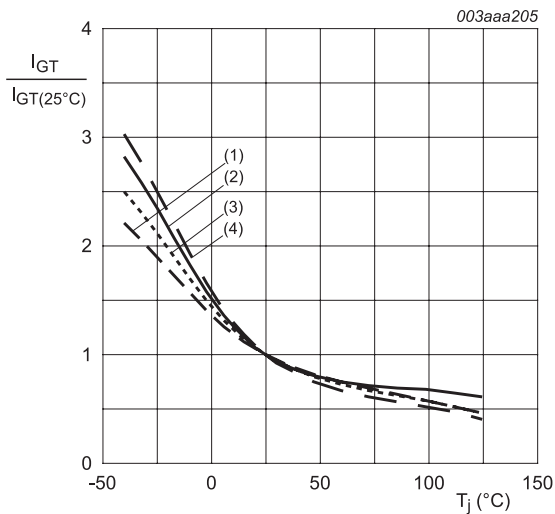


Fig. 5. Transient thermal impedance from junction to lead as a function of pulse width

## 10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Static characteristics							
I <sub>GT</sub>	gate trigger current	V <sub>D</sub> = 12 V; I <sub>T</sub> = 0.1 A; T2+ G+; T <sub>J</sub> = 25 °C; <a href="#">Fig. 6</a>		-	-	5	mA
		V <sub>D</sub> = 12 V; I <sub>T</sub> = 0.1 A; T2+ G-; T <sub>J</sub> = 25 °C; <a href="#">Fig. 6</a>		-	-	5	mA
		V <sub>D</sub> = 12 V; I <sub>T</sub> = 0.1 A; T2- G-; T <sub>J</sub> = 25 °C; <a href="#">Fig. 6</a>		-	-	5	mA
		V <sub>D</sub> = 12 V; I <sub>T</sub> = 0.1 A; T2- G+; T <sub>J</sub> = 25 °C; <a href="#">Fig. 6</a>		-	-	10	mA
I <sub>L</sub>	latching current	V <sub>D</sub> = 12 V; I <sub>G</sub> = 0.1 A; T2+ G+; T <sub>J</sub> = 25 °C; <a href="#">Fig. 7</a>		-	-	10	mA
		V <sub>D</sub> = 12 V; I <sub>G</sub> = 0.1 A; T2+ G-; T <sub>J</sub> = 25 °C; <a href="#">Fig. 7</a>		-	-	20	mA
		V <sub>D</sub> = 12 V; I <sub>G</sub> = 0.1 A; T2- G-; T <sub>J</sub> = 25 °C; <a href="#">Fig. 7</a>		-	-	10	mA
		V <sub>D</sub> = 12 V; I <sub>G</sub> = 0.1 A; T2- G+; T <sub>J</sub> = 25 °C; <a href="#">Fig. 7</a>		-	-	10	mA
I <sub>H</sub>	holding current	V <sub>D</sub> = 12 V; T <sub>J</sub> = 25 °C; <a href="#">Fig.8</a>		-	-	10	mA
V <sub>T</sub>	on-state voltage	I <sub>T</sub> = 2 A; T <sub>J</sub> = 25 °C; <a href="#">Fig. 9</a>		-	1.35	1.65	V
V <sub>GT</sub>	gate trigger voltage	V <sub>D</sub> = 12 V; I <sub>T</sub> = 0.1 A; T <sub>J</sub> = 25 °C; <a href="#">Fig. 10</a>		-	-	1	V
		V <sub>D</sub> = 800 V; I <sub>T</sub> = 0.1 A; T <sub>J</sub> = 125 °C		0.2	-	-	V
I <sub>D</sub>	off-state current	V <sub>D</sub> = 800 V; T <sub>J</sub> = 25 °C		-	-	10	μA
		V <sub>D</sub> = 800 V; T <sub>J</sub> = 125 °C		-	-	0.5	mA
I <sub>R</sub>	reverse current	V <sub>D</sub> = 800 V; T <sub>J</sub> = 25 °C		-	-	10	μA
		V <sub>D</sub> = 800 V; T <sub>J</sub> = 125 °C		-	-	0.5	mA
Dynamic characteristics							
dV <sub>D</sub> /dt	rate of rise of off-state voltage	V <sub>DM</sub> = 536 V; T <sub>J</sub> = 110 °C; (V <sub>DM</sub> = 67% of V <sub>DRM</sub> ); exponential waveform; gate open circuit; <a href="#">Fig. 11</a>		20	-	-	V/μs
dV <sub>com</sub> /dt	rate of change of commutating voltage	V <sub>D</sub> = 400 V; T <sub>J</sub> = 110 °C; dI <sub>com</sub> /dt = 0.44 A/ms; I <sub>T</sub> = 1 A; gate open circuit		1	-	-	V/μs



- (1) T2- G+
- (2) T2- G-
- (3) T2+ G-
- (4) T2+ G+

Fig. 6. Normalized gate trigger current as a function of junction temperature

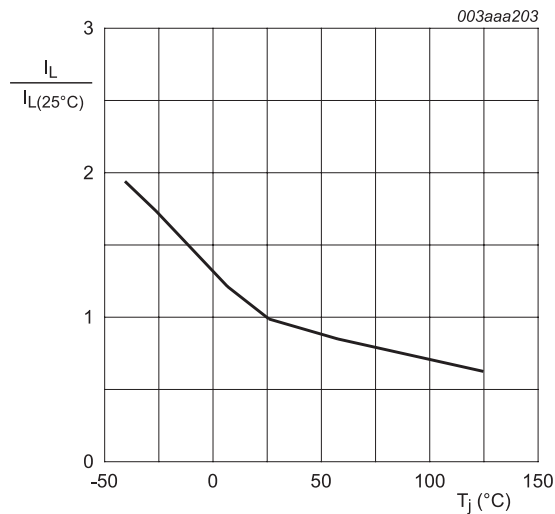


Fig. 7. Normalized latching current as a function of junction temperature

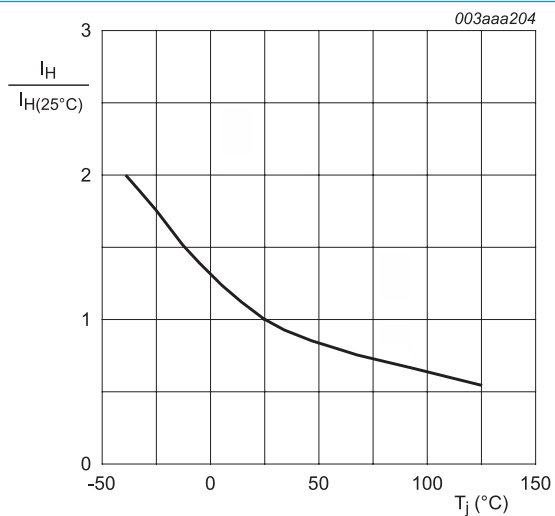
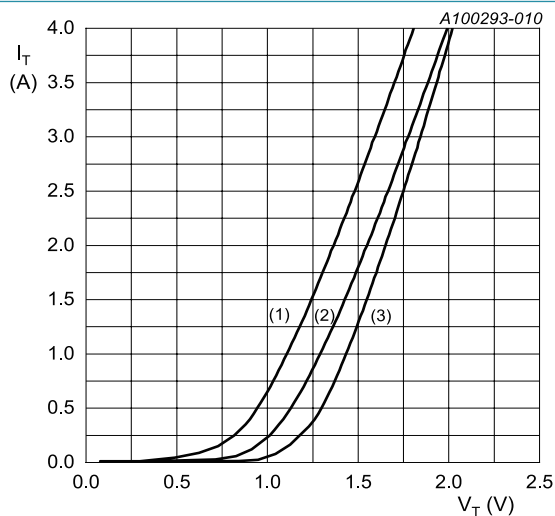


Fig. 8. Normalized holding current as a function of junction temperature



- $V_o = 1.12 \text{ V}; R_s = 0.21 \Omega$
- (1)  $T_j = 125^{\circ}\text{C}$ ; typical values
  - (2)  $T_j = 125^{\circ}\text{C}$ ; maximum values
  - (3)  $T_j = 25^{\circ}\text{C}$ ; maximum values

Fig. 9. On-state current as a function of on-state voltage



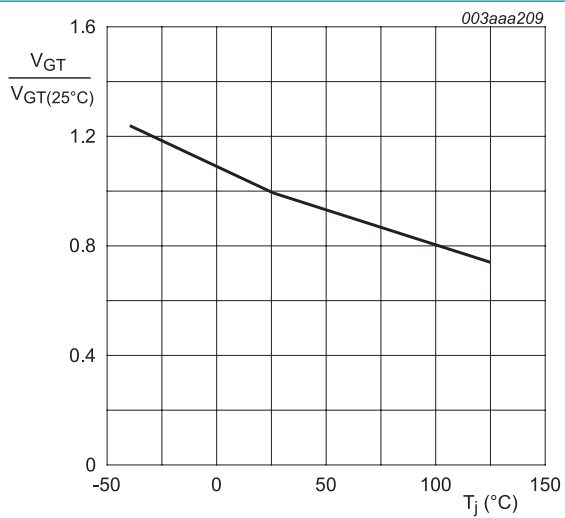
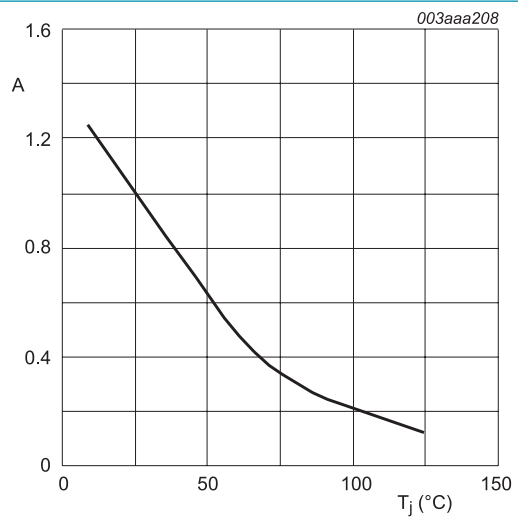


Fig. 10. Normalized gate trigger voltage as a function of junction temperature



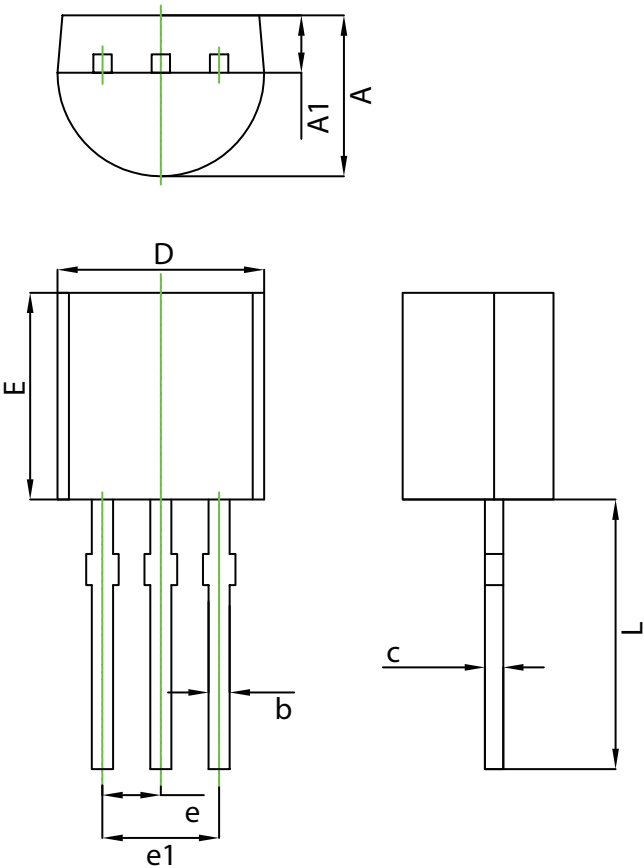
$$A = \frac{dV_D(T_j^{\circ}\text{C})/dt}{dV_D(25^{\circ}\text{C})/dt}$$

Fig. 11. Normalized critical rate of rise of off-state voltage as a function of junction temperature; typical values

11. Package outline

Plastic single-ended leaded(through hole) package; 3 leads

TO92



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	3.300	3.700	0.130	0.146
A1	1.100	1.400	0.043	0.055
b	0.380	0.550	0.015	0.022
c	0.360	0.510	0.014	0.020
D	4.300	4.700	0.169	0.185
E	4.300	4.700	0.169	0.185
e	1.270 TYP.		0.050 TYP.	
e1	2.440	2.640	0.096	0.104
L	14.100	14.500	0.555	0.571

## 12. Legal information

### Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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